

METHOD OF DEFECT REVIEW

Abstract

A method of defect review. First, a wafer with a plurality of defects is provided. A defect inspection is performed to detect the defects. An automatic defect classification is then performed to divide the defects into different defect types according to a predetermined database. A defect review is performed to review different defect types of defects which are sampled in different weights according to yield killing ratios of each defect types.